**IEEE Journal on Flexible Electronics**

**Call for Papers**

**Special Issue on Papers from IEEE FLEPS 2022**

Flexible and printable sensor systems have sparked much interest in recent years. New technologies, such as additive printing manufacturing, laser patterning, 3D printing are being developed in order to realize a diverse range of readily deployable systems, such as sensors, displays, and smart tags on flexible, disposable, stretchable and degradable substrates. Technologies developed for silicon-based planar electronics and solid-state sensors are also being repurposed to suit the needs of the expanding area of flexible, printable sensors and systems. This trend is expected to continue since all market indications point to strong development in this sector. This is also reflected by the large number of high-quality papers presented at IEEE FLEPS 2022 Conference which focused on novel printable and solution-processable nanomaterials and printing techniques.

This Special Journal Issue will provide an opportunity for IEEE FLEPS 2022 authors to submit expanded versions of their works presented at the conference. Authors are encouraged to submit papers on theoretical, technical, and experimental aspects of the design, development, and validation of different kinds of innovative sensors and systems printed or solutions processed on a variety of substrates, such as planar substrates including plastic, metal foils, paper, and so on.

# Topics of Interest

* Stretchable/Shrinkable Sensors and Electronics
* Hybrid Systems-in-Foil
* Biomedical sensing devices
* Electronic textile/paper/skin
* Flexible/Printable Electronics in context with Circular Economy
* Organic/Inorganic/Hybrid Flexible Sensors and Electronics
* Printable batteries, energy harvesters
* Wearable sensors
* Sensors for health monitoring
* Printable displays, lighting sources
* Packaging
* Smart tags, RFID tags, etc.
* Modeling of printable sensors
* Manufacturing Techniques (including Printing)
* Emerging Materials for Flexible and Printable Systems
* 3D printing

# Important dates (tentative)

**31, August 2022:** Deadline for Paper Submission

**15, November 2022:**  Completion of First Review

**31, January 2023:** Completion of Final Review

**31, March 2023:**  Publication

# Guest Editors

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# Submission and Peer Review of Papers

All papers shall undergo the standard IEEE J-FLEX peer-review process. Manuscripts must be submitted online, via the *IEEE Manuscript CentralTM*, see https://mc.manuscriptcentral.com/jflex. When submitting, please indicate in the “Manuscript Type” roll down menu, and also by e‐mail to John Wright, john.wright@ieee.org, that the paper is intended for the “**Special Issue on Papers from IEEE FLEPS 2022**” Special Issue. Authors are particularly encouraged to **suggest names of potential reviewers** for their manuscripts in the space provided for these recommendations in *Manuscript Central.* For manuscript preparation and submission, please follow the guidelines in the *Information for Authors* at the IEEE J-FLEX web page, <https://ieee-jflex.org/guidelines-for-authors/>.